

REQUEST FOR QUOTATION

Date: _____ Signature: _____

Customer: _____	Phone: _____
Address: _____	Fax: _____
Customer Contact: _____	E-mail: _____

PCB Identification No.	Rev.	Type of Offer	Offer Quantity	Order Quantity	Delivery Date
PPC Ident. No.: ID_ _____	_____	<input type="checkbox"/> Prototypes <input type="checkbox"/> Series	_____	_____	_____
Layer Count: _____ Layer Multilayer					
ML Build-up: <input type="checkbox"/> PPC Standard Build-up <input type="checkbox"/> Customer Build-up (Please enclose Build-up)					
Material: <input type="checkbox"/> FR4 <input type="checkbox"/> others: _____					
PCB Thickness: _____ ± _____ mm (Excl. Cu-cladding)					
Dimensions: L _____ mm W _____ mm					
Drilling Datas:					
Hole Count per PCB: _____		thereof Blind Vias: _____		thereof Buried Vias: _____	
(Mechanical Drilling)					
Smallest Final Hole-_: _____ mm		Largest Final Hole-End-_: _____ mm			
Microvias Count per PCB: _____		<input type="checkbox"/> Solder Side over _____ Layer/-s		<input type="checkbox"/> Component Side over _____ Layer/-s	
(Laser Drilling)					
Conductive Pattern:					
Smallest Track Width/Spacing <input type="checkbox"/> OL * <input type="checkbox"/> IL * (* OL = Outer Layer / IL = Inner Layer)					
<input type="checkbox"/> > 200 µm					
<input type="checkbox"/> > 150 µm; < 200 µm					
<input type="checkbox"/> > 100 µm; < 150 µm					
<input type="checkbox"/> > 75 µm; < 100 µm					
Base Cu-Cladding		OL _____ µm		IL _____ µm	
<input type="checkbox"/> SMD <input type="checkbox"/> BGA <input type="checkbox"/> µBGA		<input type="checkbox"/> Single-sided		<input type="checkbox"/> Double-sided	
Smallest Pitch		SS _____ mm		CS _____ mm	
Surface Plating					
<input type="checkbox"/> Hot Air Levelling (HAL)		<input type="checkbox"/> PbSn IR-Reflowed			
<input type="checkbox"/> Electroless Au over Ni		<input type="checkbox"/> Electroless Sn		<input type="checkbox"/> _____	
Gold Plating:					
<input type="checkbox"/> Bonded Gold		<input type="checkbox"/> Gold Track Pattern/Edge Pads (Hardgold)		Area: _____ cm ²	
Solder Resist:					
<input type="checkbox"/> Probimer / Elpemer		<input type="checkbox"/> Screen Print		<input type="checkbox"/> Packlayer <input type="checkbox"/> none	
extras: <input type="checkbox"/> Silkscreen Print		<input type="checkbox"/> on CS <input type="checkbox"/> on SS		<input type="checkbox"/> White (Standard) <input type="checkbox"/> _____	
<input type="checkbox"/> Peelable Solder Resist on SS (acc. Plan/Film)		<input type="checkbox"/> _____			
<input type="checkbox"/> Via Plugging (Additional screen printing step)					
Specialities:					
<input type="checkbox"/> Controlled Impedance		∩ No. of Impedance Layers: _____ ; Values: _____			
<input type="checkbox"/> Buried and/or Blind Vias		∩ (Please enclose Build-up)			
<input type="checkbox"/> Buried Capacitance					
<input type="checkbox"/> Metallcore and/or Heatsink		∩ (Special specifications required)			
<input type="checkbox"/> PCB Multi-Panel		No. of PCBs per Panel: _____		<input type="checkbox"/> Routed <input type="checkbox"/> Scribed	
<input type="checkbox"/> Defective PCBs in Panel Allowed					
<input type="checkbox"/> Special Panel Frame		Dimensions: _____ mm ; (Please enclose drawing)			
<input type="checkbox"/> Customer Test Coupons					
Press-fit Technology:					
<input type="checkbox"/> Press-fit Assembly		∩ (Special specifications required)			
Enclosed Datas/Documentation:					
<input type="checkbox"/> Data Transmission (Mailbox/FTP-Server)		∩ (Infos see: www.ppc-electronic.com)			
⇒ To be filled out by TVM / TS PPC Electronic AG!					
Flying Probe:		<input type="checkbox"/> Yes <input type="checkbox"/> No		Date: _____ Sign.: _____	
Feasibility confirmed:		<input type="checkbox"/> Yes <input type="checkbox"/> No			
Remarks:					

